

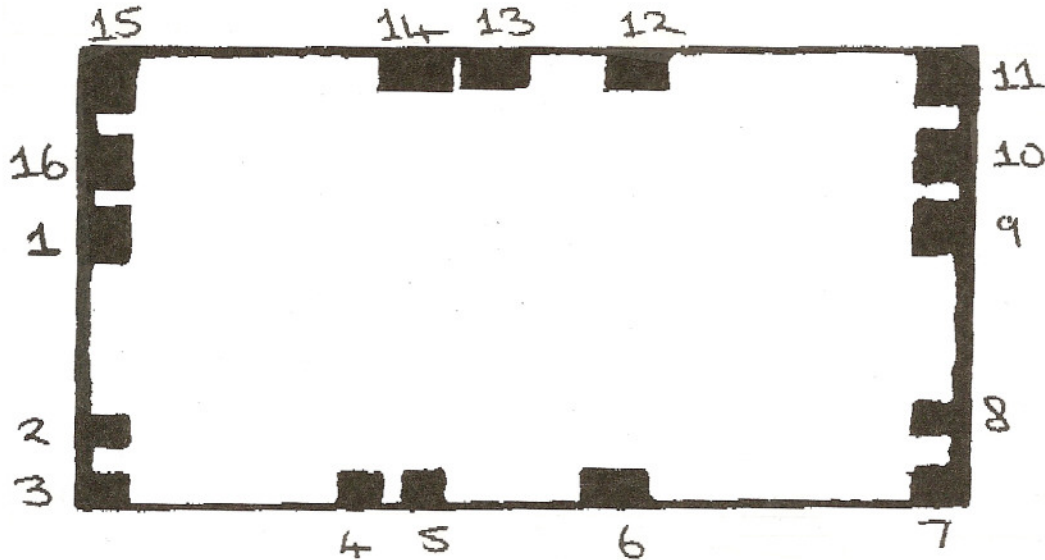


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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



<u>Pad</u>	<u>Function</u>	<u>Pad</u>	<u>Function</u>
1	BHB	9	AHB
2	BHI	10	AHO
3	BLI	11	AHS
4	ALI	12	V _{DD}
5	DEL	13	ALO
6	V _{SS}	14	BLO
7	AHI	15	BHS
8	DIS	16	BHO

Topside Metal: Al

Backside: Si

Backside Potential:

Mask Ref: Issue 1

Bond Pads : .003 min

APPROVED BY: CB

MFG: Harris

DIE SIZE: .108" x .068"

THICKNESS: .020"

DATE: 2/6/01

P/N: HIP4082